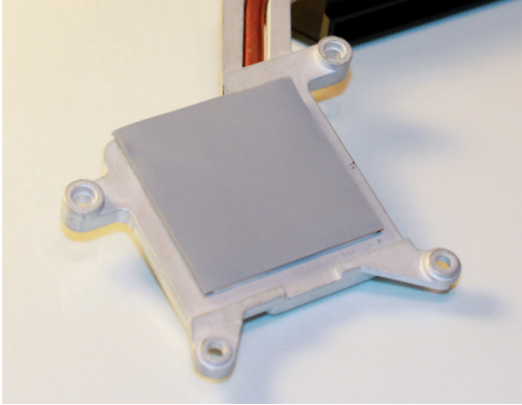


TG-X2

Ultra Soft Thermal Conductive Pad



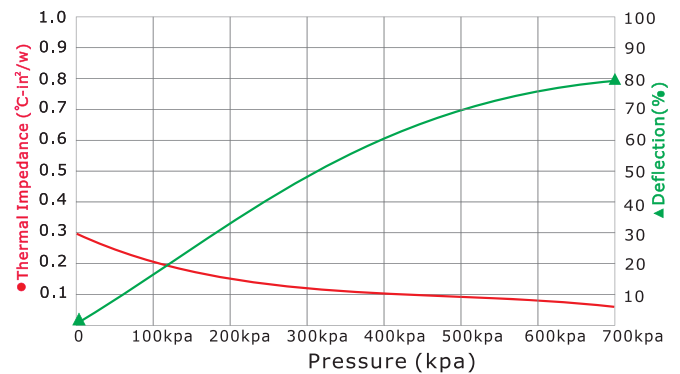
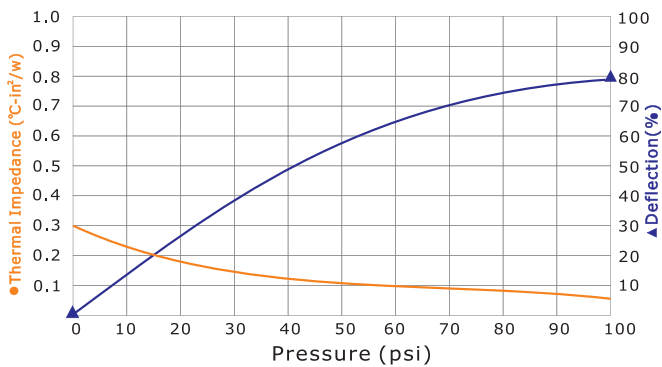
Features

- Superior thermal conductivity
- Highly compressible
- Naturally tacky
- Low Shore 00 hardness
- Low oil bleed
- Electrically insulating

Applications

- Electronic components: IC / CPU / MOS
- LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....
- DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection

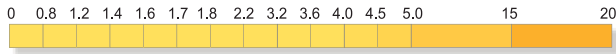


Properties

- REACH Compliant
- RoHS Compliant

Thermal Conductivity: 12 W/mK
(W/mK - Z Axis)

Hardness: 0 (Shore 00)
(Shore 00)



Testing sample thickness: 1.5mm

In the thermal resistance vs pressure vs deflection charts TG-X2 provides low thermal impedance.

As the pressure increases the thermal impedance decreases. TG-X2 provides good compliance and softness.

| Property | TG-X2 | Unit | Test Method |
|-----------------------------------|-------------------|----------|-------------|
| Colour | Grey | - | Visual |
| Operating Temperature Range | -45 to 200 | °C | - |
| Density | 3.4 | - | - |
| Thermal Conductivity | 12 | W/mK | ASTM D5470 |
| Hardness | 0 | Shore 00 | ASTM D2240 |
| t=1mm Thermal Impedance @ 10psi | 0.11 | °c in²/W | ASTM D5470 |
| t=1mm Thermal Impedance @ 50psi | 0.09 | °c in²/W | ASTM D5470 |
| t=1mm Thermal Impedance @ 10psi | 0.04 | °c in²/W | ASTM D5470 |
| t=1mm Percent Deflection @ 10psi | 24 | % | - |
| t=1mm Percent Deflection @ 50psi | 63 | % | - |
| t=1mm Percent Deflection @ 100psi | 81 | % | - |
| Volume Resistance | >10 ¹⁰ | Ohm-cm | ASTM D257 |
| Total Mass Loss | <0.4 | % | ASTM E595 |
| Flammability Rating | V-0 | - | UL 94 |
| Breakdown Voltage | 13 | kV | ASTM D149 |

